

WHAT IS CLAIMED IS:

1                    1.        An integrated circuit comprising a plurality of dynamically adjustable  
2 impedance termination circuits that are coupled together in parallel to a first pin, each of the  
3 impedance termination circuits comprising:

4                    first resistors coupled in parallel;  
5                    a second resistor coupled in series with the first resistors;  
6                    first pass gates each coupled in series with one of the first resistors and each  
7 coupled to a first control signal; and  
8                    a second pass gate coupled to the first pass gates and coupled to receive a  
9 second control signal.

1                    2.        The integrated circuit according to claim 1 wherein the first resistors  
2 comprise three resistors coupled in parallel.

1                    3.        The integrated circuit according to claim 1 wherein the integrated  
2 circuit comprises three of the impedance termination circuits coupled together in parallel to  
3 the first pin.

1                    4.        The integrated circuit according to claim 1 wherein each of the first  
2 pass gates and the second pass gates comprise a p-channel transistor and an n-channel  
3 transistor coupled together in parallel.

1                    5.        The integrated circuit according to claim 1 wherein the integrated  
2 circuit includes a second set of impedance termination circuits that are coupled together in  
3 parallel to a second pin, the first and the second pin being differential input/output pins.

1                    6.        A method for providing dynamically adjustable on-chip termination  
2 impedance to a first input/output pin on an integrated circuit, the method comprising:  
3                    controlling first current paths through first on-chip resistors that coupled  
4 together in parallel using first pass gates, each first pass gate being coupled in series with one  
5 of the first on-chip resistors;  
6                    providing a second current path through the first on-chip resistors and a  
7 second on-chip resistor that is coupled in series with the first on-chip resistors by turning ON  
8 a second pass gate;

9                    providing a third current path through a third on-chip resistor that is coupled in  
10 parallel with the first and the second on-chip resistors by turning ON a third pass gate,  
11 wherein the second and the third resistors are coupled to the first pin;  
12                    sensing the on-chip termination impedance; and  
13                    dynamically adjusting the on-chip termination impedance by changing states  
14 of the first pass gates.

1                    7.        The method of claim 6 further comprising:  
2                    coupling fourth on-chip resistors together in parallel by turning ON fourth  
3 pass gates, each fourth pass gate being coupled in series with one of the fourth resistors,  
4                    wherein the fourth on-chip resistors are coupled in series with the third resistor  
5 and the second current path flows through the fourth resistors.

1                    8.        The method of claim 7 further comprising:  
2                    blocking current through a fifth resistor coupled in parallel with the first and  
3 the second on-chip resistors by turn OFF a fifth pass gate.

1                    9.        The method of claim 7 further comprising:  
2                    blocking current through a selected one of the fourth resistors by turning OFF  
3 one of the fourth pass gates that is coupled to the selected fourth resistor.

1                    10.      The method of claim 6 further comprising:  
2                    blocking current through a selected one of the first resistors by turning OFF  
3 one of the first pass gates that is coupled the selected first resistor.

1                    11.      The method of claim 6 further comprising:  
2                    decoupling a third on-chip resistor from the first on-chip resistors by turning  
3 OFF a third pass gate; and  
4                    blocking a fourth current path through a fourth on-chip resistor that is coupled  
5 in parallel with the first and the second on-chip resistors by turning OFF a fourth pass gate.

1                    12.      The method of claim 6 wherein the integrated circuit is a field  
2 programmable gate array.

1                    13.      The method of claim 6 further comprising providing on-chip  
2 termination impedance to a second input/output pin on the integrated circuit by:

3 coupling fourth on-chip resistors together in parallel by turning ON fourth  
4 pass gates, each fourth pass gate being coupled in series with one of the fourth on-chip  
5 resistors;  
6 providing a fourth current path through the fourth on-chip resistors and a fifth  
7 on-chip resistor coupled in series with the fourth on-chip resistors by turning ON a fifth pass  
8 gate,  
9 wherein the first and the second pins are differential pins.

1 14. An integrated circuit comprising a first dynamically adjustable on-chip  
2 impedance termination circuit, wherein the first impedance termination circuit comprises:  
3 means for coupling together first resistors in parallel in response to first  
4 control signals;  
5 means for providing a first current path through a second resistor coupled in  
6 series with the first resistors in response to a second control signal; and  
7 means for providing a second current path through a third resistor coupled in  
8 parallel with the first resistors and the second resistor in response to a third control signal,  
9 wherein the first, second, and third resistors provide termination impedance at a pin.

1 15. The integrated circuit as defined in claim 14 further comprising:  
2 means for blocking current through a fourth on-chip resistor that is coupled to  
3 the second and the third on-chip resistors in response to a fourth control signal.

1 16. The integrated circuit as defined in claim 14 further comprising:  
2 means for blocking current flow through one of the first resistors in response  
3 to a changed value of a corresponding one of the first control signals.

1 17. The integrated circuit as defined in claim 14 wherein the integrated  
2 circuit further comprises a second on-chip impedance termination circuit coupled to the first  
3 on-chip impedance termination circuit, wherein the second impedance termination circuit  
4 comprises:  
5 means for coupling together fourth resistors in parallel in response to fourth  
6 control signals;  
7 means for providing a third current path through a fifth resistor coupled in  
8 series with the fourth resistors in response to a fifth control signal; and

9 means for providing a fourth current path through a sixth resistor coupled  
10 parallel with the fourth resistors and the fifth resistor in response to a sixth control signal,  
11 wherein the fourth, fifth, and sixth resistors provide termination impedance at a second pin.

1 18. The integrated circuit as defined in claim 14 wherein the integrated  
2 circuit is a programmable logic device.

1 19. The integrated circuit as defined in claim 14 further comprising:  
2 means for coupling together fourth resistors in parallel in response to fourth  
3 control signals, wherein the second current path flows through the third and the fourth  
4 resistors.

1 20. The integrated circuit as defined in claim 19 further comprising:  
2 means for providing a third current path through a fifth resistor coupled  
3 parallel with the fourth and the third resistors in response to a fifth control signal.